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(54) Title: LIQUID COMPOSITIONS FOR SELECTIVELY REMOVING POLYSILICON OVER P-DOPED SILICON AND SILICON-GERMANIUM DURING MANUFACTURE OF A SEMICONDUCTOR DEVICE

(57) Abstract: Described herein is an etching solution suitable for the selective removal of silicon over p-doped silicon and/or silicon-germanium from a microelectronic device, having water; at least one of NH₄OH or a quaternary ammonium hydroxide; at least one compound selected from benzoquinone or a derivative of benzoquinone; quinoline or a derivative of quinoline; an unsubstituted or substituted C₆₋₂₀ aliphatic acid; a C₄₋₁₂ alkylamine; and a polyalkylenimine; optionally at least one water-miscible organic solvent; and optionally, at least one compound selected from an alkanolamine and a polyamine.



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